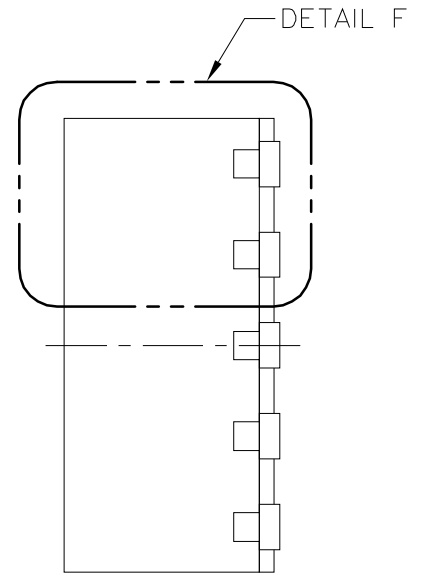
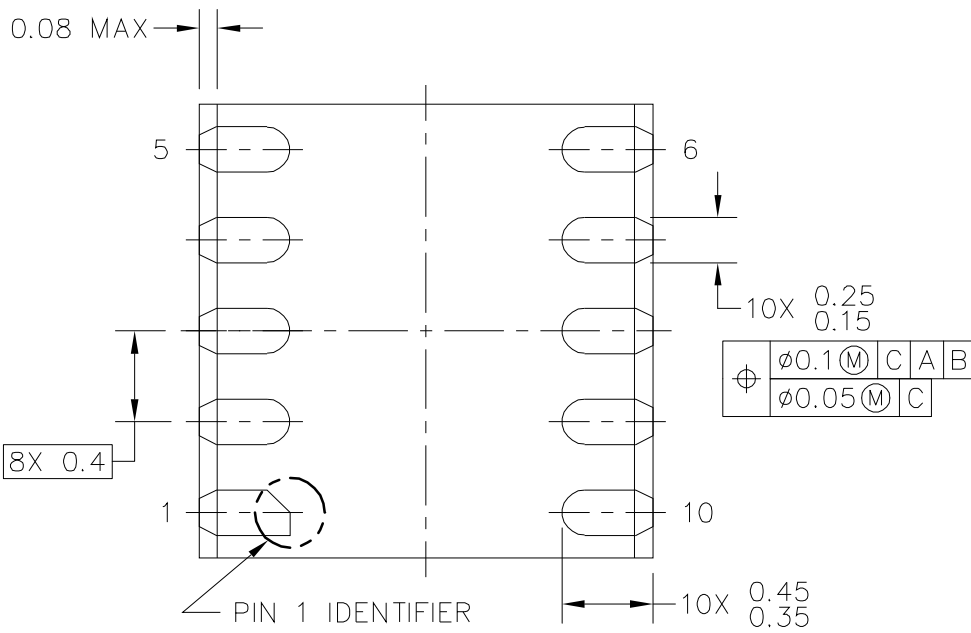


TOP VIEW

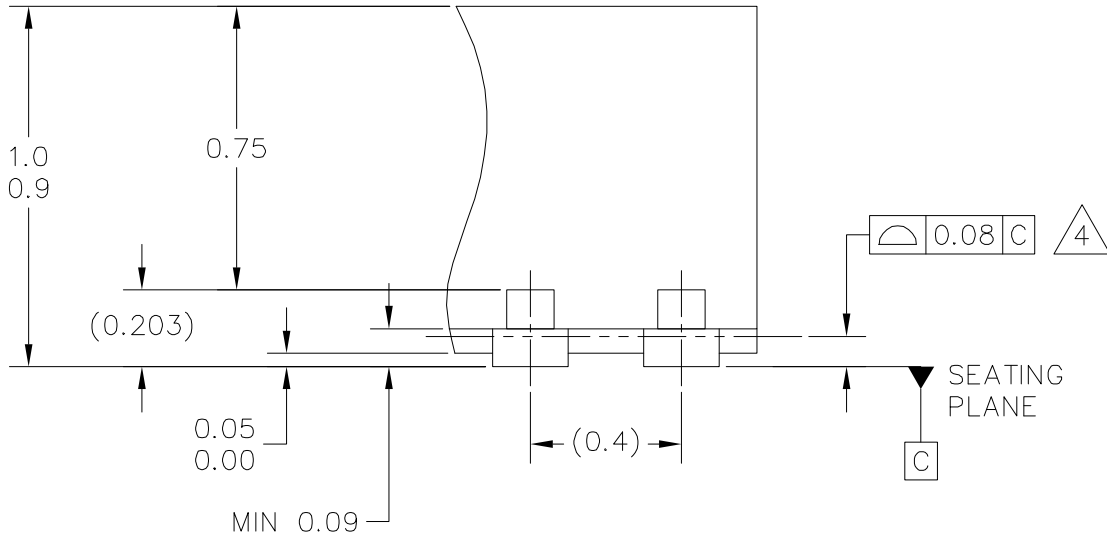


SIDE VIEW



BOTTOM VIEW

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	<b>MECHANICAL OUTLINE</b>	PRINT VERSION NOT TO SCALE	
TITLE: DFN-COL, PLASTIC DUAL FLAT NON-LEADED PACKAGE, 2 X 2 X 0.95, 0.4 PITCH, 10 TERMINAL		DOCUMENT NO: 98ASA00979D	REV: B
		STANDARD: NON-JEDEC	
		SOT1615-3	18 MAY 2017




DETAIL F  
VIEW ROTATED 90°CW

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	<b>MECHANICAL OUTLINE</b>	PRINT VERSION NOT TO SCALE	
TITLE: DFN-COL, PLASTIC DUAL FLAT NON-LEADED PACKAGE, 2 X 2 X 0.95, 0.4 PITCH, 10 TERMINAL		DOCUMENT NO: 98ASA00979D	REV: B
		STANDARD: NON-JEDEC	
		SOT1615-3	18 MAY 2017



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THIS IS A NON-JEDEC REGISTERED PACKAGE.
4.  COPLANARITY APPLIES TO LEADS.
5. TOTAL THICKNESS DOES NOT INCLUDE BURR.

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	<b>MECHANICAL OUTLINE</b>	PRINT VERSION NOT TO SCALE	
TITLE: DFN-COL, PLASTIC DUAL FLAT NON-LEADED PACKAGE, 2 X 2 X 0.95, 0.4 PITCH, 10 TERMINAL		DOCUMENT NO: 98ASA00979D	REV: B
		STANDARD: NON-JEDEC	
		SOT1615-3	18 MAY 2017